

Bill of Materials

	SCM	SCC	Remarks
Die Attach	<u>Upper Die</u> QMI536 <u>Bottom Die</u> Ablestik 3230	<u>Upper Die</u> QMI536 <u>Bottom Die</u> Ablestik 3230	Same BOM
Wire type	Gold MKE UR2	Gold MKE UR2	
Mold Compound	Sumitomo G770	Sumitomo G770	
Lead Finish	Matte Sn	Matte Sn	

Reliability Qualification Plan for Stacked-die LFCSP Package at STATS ChipPAC China (SCC)

QUALIFICATION PLAN			
Test	Conditions	Sample Size	Expected Completion Date
Highly Accelerated Stress Test (HAST)*	JEDEC <i>JESD22-A110</i>	3 x 77	April 2014
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	3 x 77	April 2014
Autoclave (AC)*	JEDEC <i>JESD22-A102</i>	3 x 77	April 2014
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	3 x 11	April 2014
High Temperature Storage Life (HTSL)	JEDEC <i>JESD22-A103</i>	1 x 77	April 2014
Field Induced Charged Device Model (FICDM)	JEDEC <i>JESD22-C101</i>	3/Voltage	April 2014

*Preconditioned per JEDEC/IPC J-STD-020